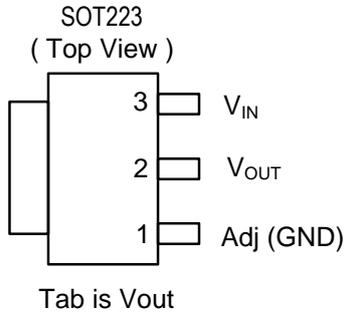




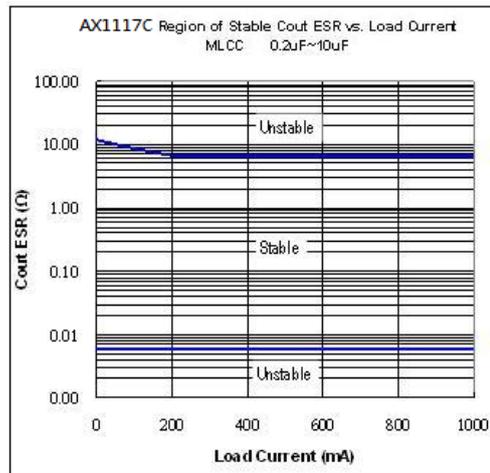
❖ **PIN ASSIGNMENT**

The packages of AX1117C is SOT223-3L; the pin assignment is given by:



Name	Description
Adj (GND)	A resistor divider from this pin to the $V_{OUT}$ pin and ground sets the output voltage. (Ground only for Fixed-Mode)
$V_{OUT}$	The output of the regulator. <b>(Note1,2)</b>
$V_{IN}$	The input pin of regulator. Typically a large storage capacitor is connected from this pin to ground to insure that the input voltage does not sag below the minimum dropout voltage during the load transient response. This pin must always be 1.5V higher than $V_{OUT}$ in order for the device to regulate properly. <b>(Note1)</b>

Note1: To prevent oscillation, a 0.2uF minimum X7R or X5R dielectric is strongly recommended if ceramics are used as output capacitors.



Note2: A minimum of 3.3uF EL capacitor to 100uF ( $10m\Omega \leq ESR \leq 1\Omega$ ) must be connected from this pin to ground to insure stability.

**❖ ORDER/MARKING INFORMATION**

Order Information	
<p><b>AX1117C X XX X</b></p> <p>Package      Vout      Packing</p> <p>E : SOT223-3L    Blank : ADJ    Blank: Tube                      18 : 1.8V      A : Taping                      33 : 3.3V</p>	
Top Marking	
<p><b>ADJ</b></p> <p>Logo ← <b>AX</b> <sup>1 1 1 7</sup> → Part number                      C</p> <p>Y <b>WWX</b> → ID code: internal                      WW: 01~52                      Year: 8=2018                      9=2019                      B=2020                      C=2021                      D=2022                      .                      Z=2044</p>	<p><b>FIX</b></p> <p>Output Voltage ← <b>AX</b> <sup>1 1 1 7</sup> →                      C - V.V</p> <p>AX1117C-18: 1.8V    Y <b>WWX</b> → ID code: internal                      AX1117C-33: 3.3V    WW: 01~52                      Year: 8=2018                      9=2019                      B=2020                      C=2021                      D=2022                      .                      Z=2044</p>

**❖ ABSOLUTE MAXIMUM RATINGS**

Characteristics	Symbol	Rating	Unit
DC Supply Voltage	$V_{IN}$	-0.3 to 15	V
Operating Junction Temperature Range	Top	-40 to +125	°C
Maximum junction Temperature	$T_{MJ}$	150	°C
Power Dissipation (Heat sink area 5mm*5mm.) $T_A=25^{\circ}C, T_J=125^{\circ}C$	SOT-223 $P_D$	1300	mW
Power Dissipation (No heat sink ;No air flow) $T_A=25^{\circ}C, T_J=125^{\circ}C$	SOT-223 $P_D$	850	mW
Storage Temperature	$T_{ST}$	-65 to 150	°C

**❖ ELECTRICAL CHARACTERISTICS**

 (T<sub>A</sub>=25°C, Under Operating Conditions)

Characteristics	Conditions		Min	Typ	Max	Units
V <sub>IN</sub> -V <sub>OUT</sub> Resistance			1	-	-	KΩ
Operation Input Voltage			2.7	-	12	V
Reference Voltage	AX1117C-ADJ	I <sub>OUT</sub> = 10mA, T <sub>J</sub> =25°C, (V <sub>IN</sub> -V <sub>OUT</sub> )=1.5V	1.225	1.250	1.275	V
Output Voltage	AX1117C-1.8	I <sub>OUT</sub> = 10mA, T <sub>J</sub> = 25°C, 3.3V ≤ V <sub>IN</sub> ≤ 12V	1.764	1.800	1.836	V
	AX1117C-3.3	I <sub>OUT</sub> = 10mA, T <sub>J</sub> = 25°C, 4.8V ≤ V <sub>IN</sub> ≤ 12V	3.235	3.300	3.365	V
Line Regulation	AX1117C-XXX	I <sub>OUT</sub> = 10mA, V <sub>OUT</sub> +1.5V < V <sub>IN</sub> < 12V, T <sub>J</sub> =25°C (Note 1,2)	-	0.2	0.5	%

**ELECTRICAL CHARACTERISTICS (CONTINUOUS)**

 (T<sub>A</sub>=25°C, Under Operating Conditions)

Characteristics	Conditions		Min	Typ	Max	Units
Load Regulation	AX1117C-ADJ	V <sub>IN</sub> =2.7V, 10mA ≤ I <sub>OUT</sub> ≤ 1A, T <sub>J</sub> =25°C (Note 1,2)	-	0.4	1	%
	AX1117C-1.8	V <sub>IN</sub> =3.3V, 0mA ≤ I <sub>OUT</sub> ≤ 1A, T <sub>J</sub> =25°C (Note 1,2)	-	15	18	mV
	AX1117C-3.3	V <sub>IN</sub> =5V, 10mA ≤ I <sub>OUT</sub> ≤ 1A, T <sub>J</sub> =25°C (Note 1,2)	-	26	33	mV
Dropout Voltage (V <sub>IN</sub> -V <sub>OUT</sub> )	AX1117C-ADJ/1.8/3.3	I <sub>OUT</sub> = 1A, ΔV <sub>OUT</sub> =1%V <sub>OUT</sub>	-	1.2	1.4	V
Current Limit	AX1117C-ADJ/1.8/3.3	(V <sub>IN</sub> -V <sub>OUT</sub> ) = 1.5V	1.0	-	-	A
Minimum Load Current	AX1117C-XXX	0°C ≤ T <sub>J</sub> ≤ 125°C	-	5	7	mA
Adjust pin current	AX1117C-ADJ	(V <sub>IN</sub> -V <sub>OUT</sub> ) = 1.5V, I <sub>OUT</sub> =10mA	-	50	100	uA
Ripple Rejection	F=120Hz, C <sub>OUT</sub> =10μf, 0.2μf AX1117C-XX, (V <sub>IN</sub> -V <sub>OUT</sub> ) = 1.5V		50	60	70	dB
Temperature Stability	I <sub>OUT</sub> =10mA		-	0.5	-	%
Thermal shutdown Temp (Over temperature protect)			-	145	-	°C
Thermal Shutdown Hysteresis			-	40	-	°C

**ELECTRICAL CHARACTERISTICS (CONTINUOUS)**

(T<sub>A</sub>=25°C, Under Operating Conditions)

Characteristics	Conditions	Min	Typ	Max	Units
θ <sub>JA</sub> Thermal Resistance Junction-to-Ambient (Note4)	SOT-223	-	75		°C/W
Thermal Resistance Junction-to-Ambient (No heat sink ;No air flow)	SOT-223	-	117	-	°C/W
θ <sub>JC</sub> Thermal Resistance Junction-to-Case	SOT-223	-	15	-	°C/W

Note1: See thermal regulation specifications for changes in output voltage due to heating effects. Line and load regulation are measured at a constant junction temperature by low duty cycle pulse testing. Load regulation is measured at the output lead = 1/18" from the package.

Note2: Line and load regulation are guaranteed up to the maximum power dissipation of 6W. Power dissipation is determined by the difference between input and output differential and the output current. Guaranteed maximum power dissipation will not be available over the full input/output range.

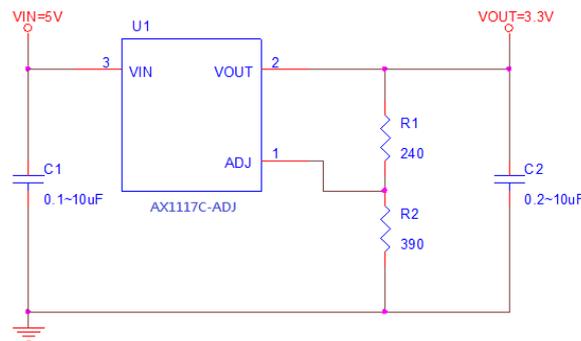
Note3: Quiescent current is defined as the minimum output current required in maintaining regulation. At 12V input/output differential the device is guaranteed to regulate if the output current is greater than 10mA.

Note4: Tab is connected to the multi-layer PCB copper area 5mm\*5mm.

**❖ APPLICATION CIRCUIT**

**(1) Using Multilayer Ceramic Capacitor (MLCC)**

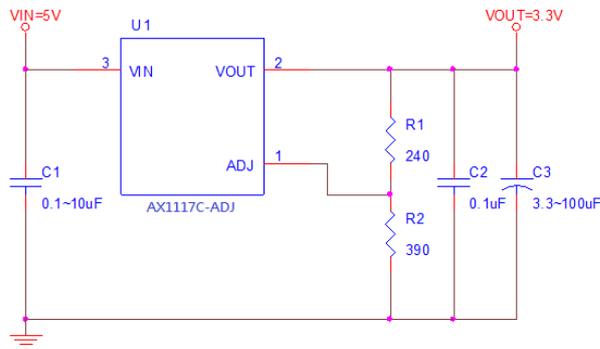
**ADJ Output**



$$V_{OUT} = V_{REF} \times \left(1 + \frac{R2}{R1}\right); V_{REF} = 1.250V$$

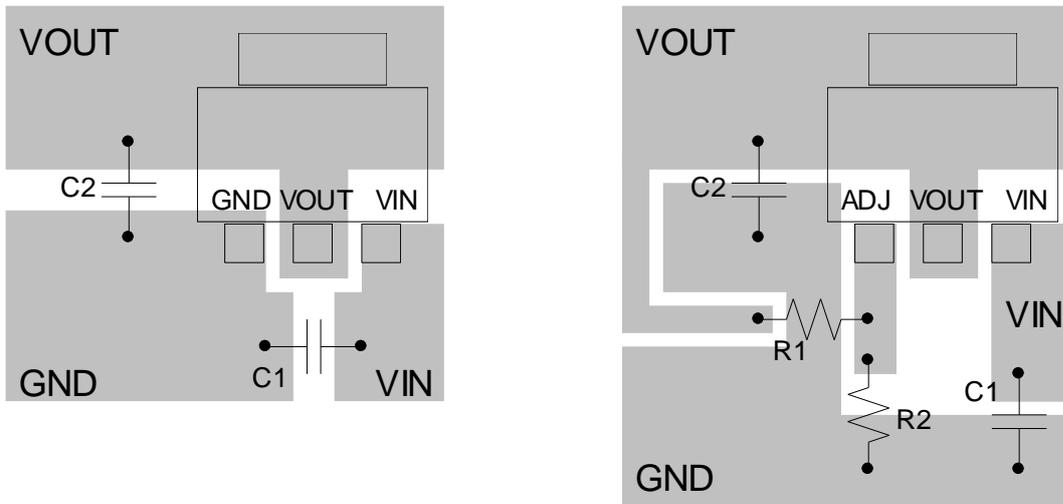
(2) Using Aluminum Electrolytic Capacitor (AL)

ADJ Output

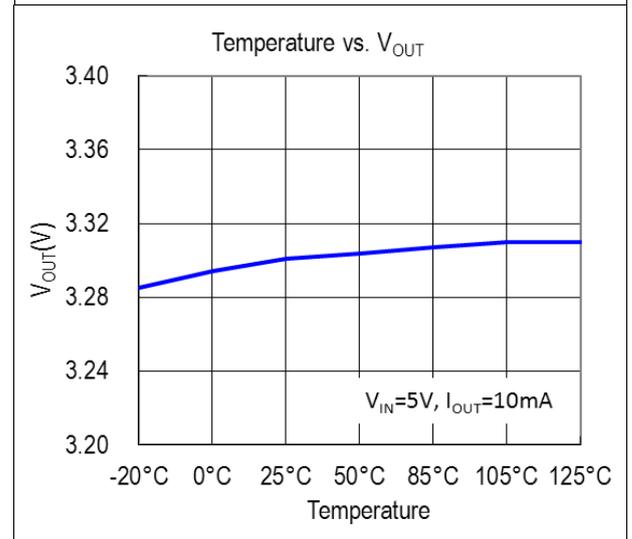
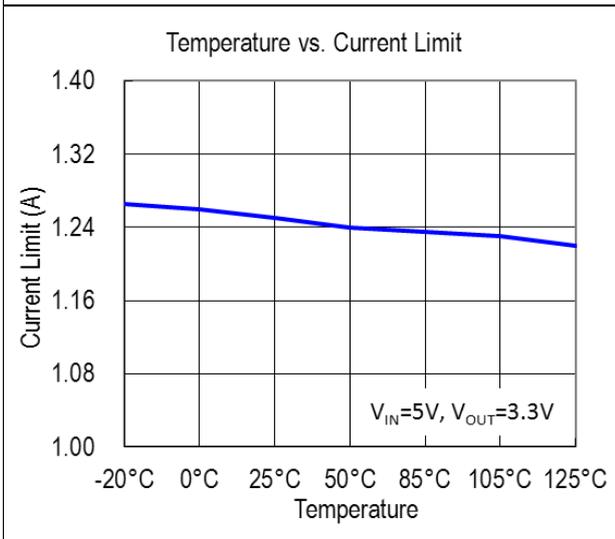
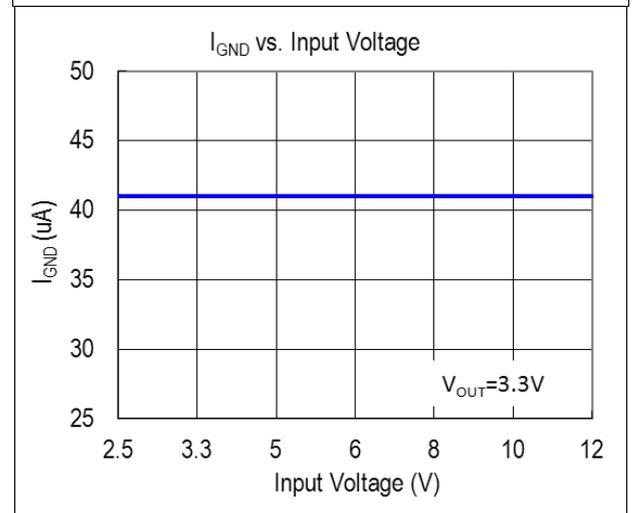
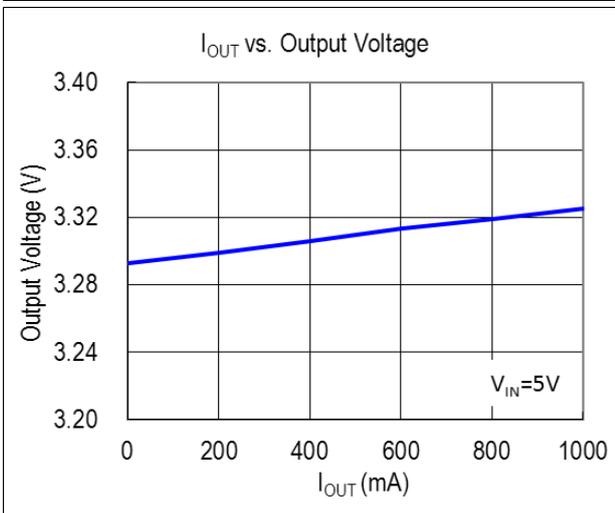
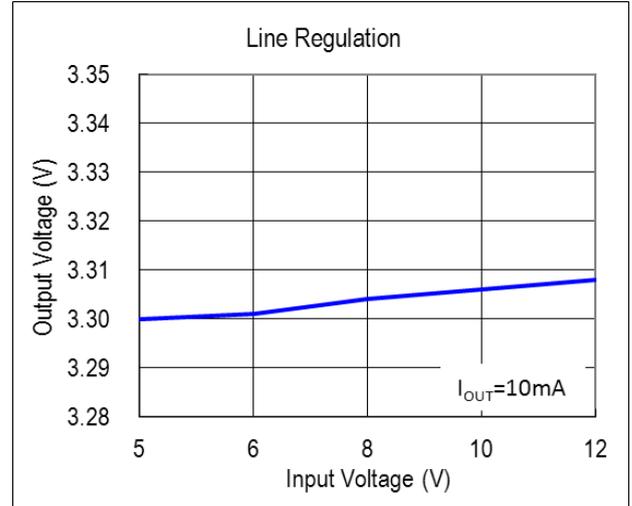
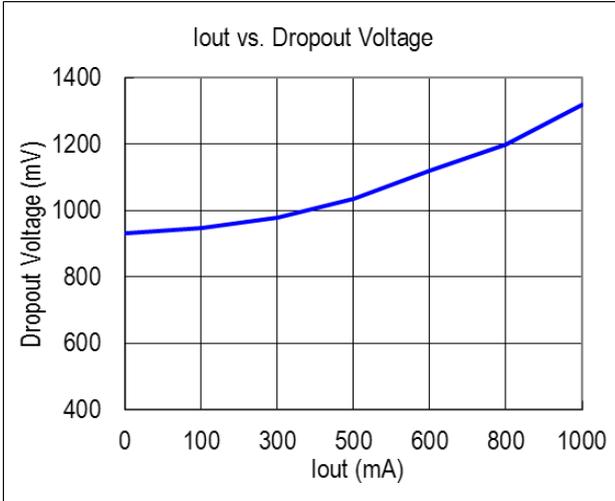


$$V_{OUT} = V_{REF} \times \left(1 + \frac{R2}{R1}\right); V_{REF} = 1.250V$$

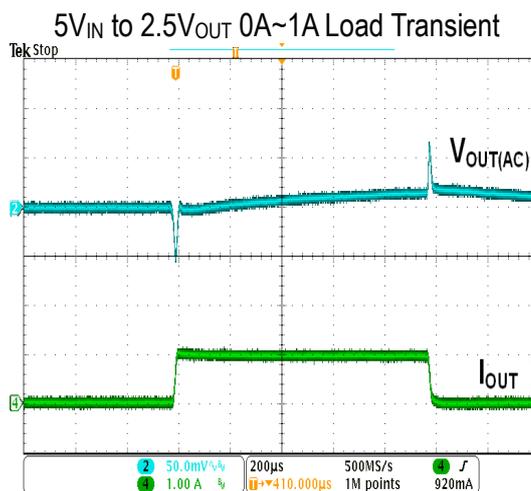
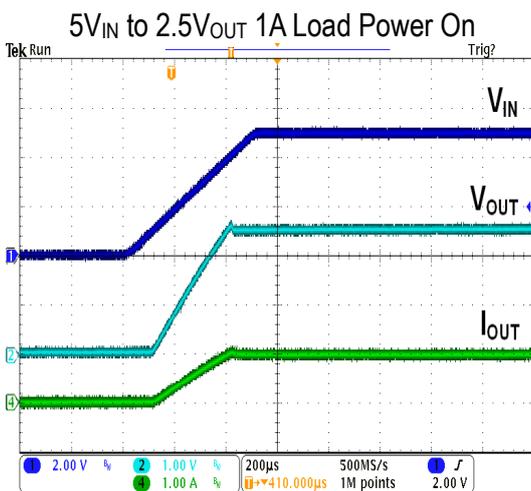
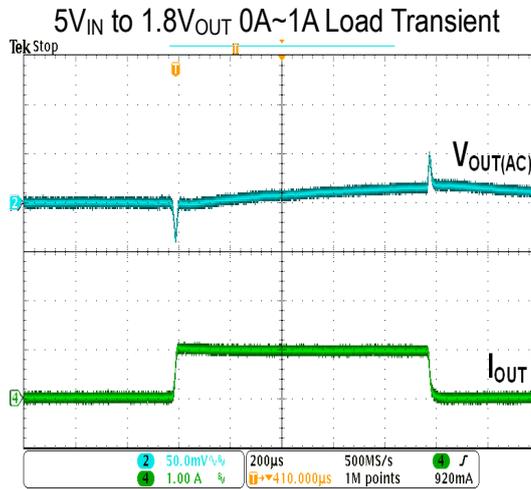
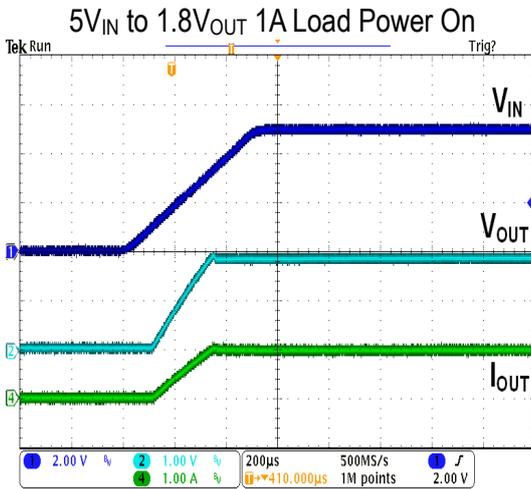
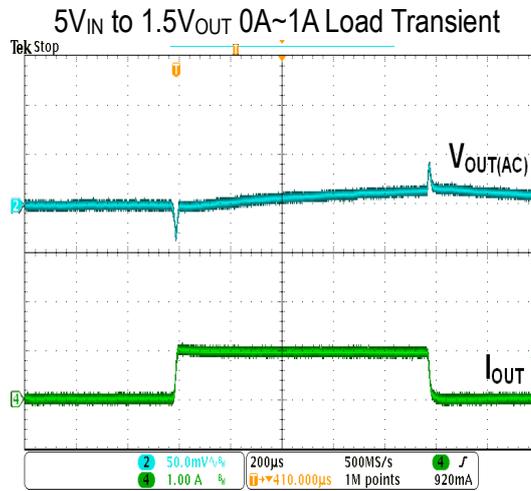
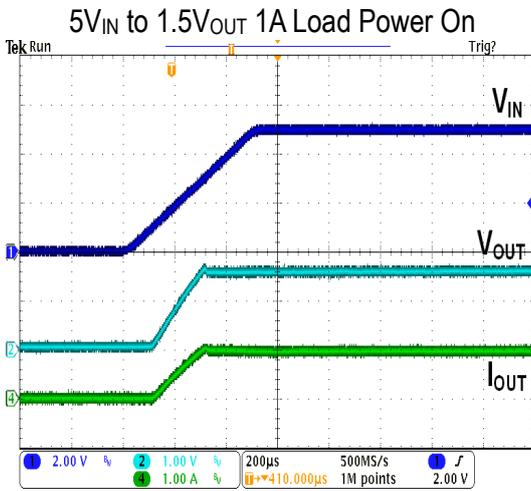
Layout Guide



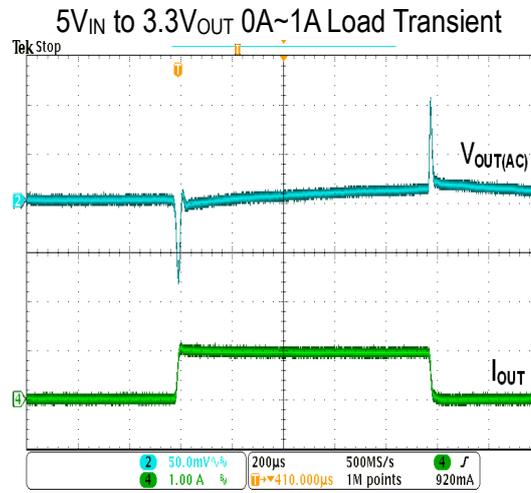
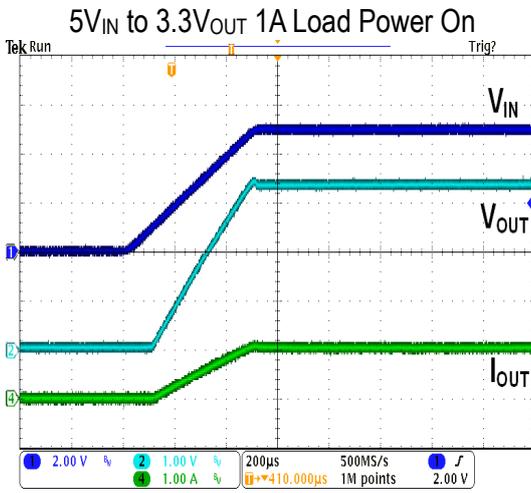
Best performance is achieved by placing C1 and C2 on the same side of the PCB as the AX1117C, and as close as is practical to the package. The ground connections for C1 and C2 should be back to the AX1117C ground plane using as wide, and as short, of a copper trace as is practical. To ensure the device does not overheat, connect the pad to VOUT plane with an appropriate amount of copper PCB area.

**❖ TYPICAL CHARACTERISTICS**


❖ TYPICAL CHARACTERISTICS (CONTINUOUS)

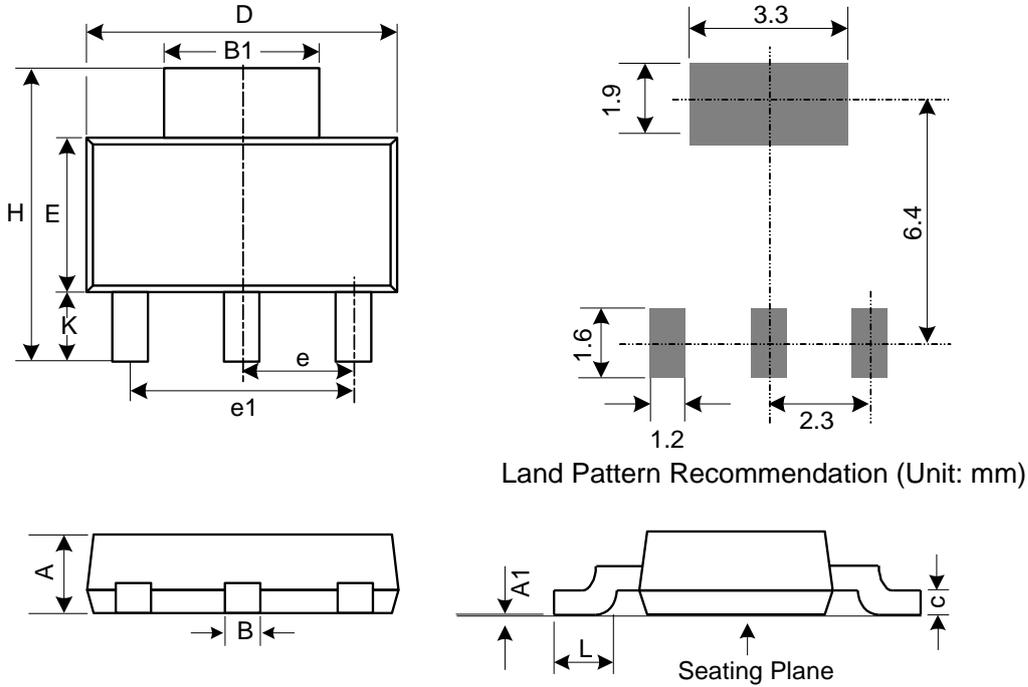


❖ TYPICAL CHARACTERISTICS (CONTINUOUS)



❖ PACKAGE OUTLINES

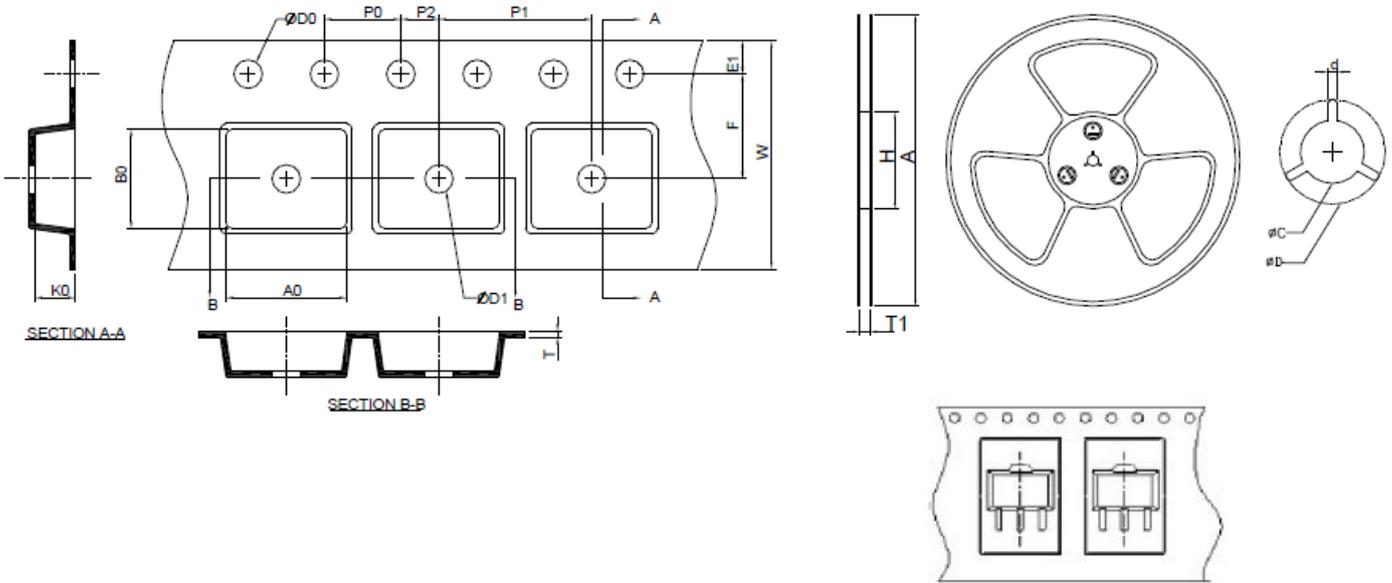
SOT223-3L



Symbol	Dimensions in Millimeters			Dimensions in Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	1.8	-	-	0.071
A1	0.02	0.06	0.1	0.001	0.002	0.004
B	0.66	0.75	0.84	0.026	0.03	0.033
B1	2.9	3	3.1	0.114	0.118	0.122
C	0.23	0.315	0.35	0.009	0.012	0.014
D	6.3	6.5	6.7	0.248	0.256	0.264
E	3.3	3.5	3.7	0.13	0.138	0.146
H	6.7	7	7.3	0.264	0.278	0.287
L	0.75	-	-	0.03	-	-
K	1.5	1.75	2	0.059	0.069	0.079
e	2.3 Basic			0.091 Basic		
e1	4.6 Basic			0.181 Basic		

JEDEC outline: TO-261 AB

## ❖ Carrier tape dimension

**SOT223-3L**


Application	A	H	T1	C	d	D	W	E1	F
SOT-223	320.0±2.00	50 MIN.	12.4+2.00 -0.00	13.0+0.50 -0.20	1.5 MIN.	20.2 MIN.	12.00±0.30	1.75±0.10	5.50±0.05
	P0	P1	P2	D0	D1	T	A0	B0	K0
	4.00±0.10	8.00±0.10	2.00±0.50	1.5+0.10 -0.00	1.5 MIN.	0.6+0.00 -0.40	6.90±0.20	7.50±0.20	2.10±0.20